

# Tracking particles at fluences $1E16 - 1E17$ n/cm<sup>2</sup>

At HL-LHC, in the inner layers of the tracker, fluences will be of the order of

$$\Phi = 2-3E16 \text{ n/cm}^2$$

→ In the present plan, Silicon detectors are replaced once at HL-LHC.

→ At FCC (?) fluences will be much higher, let's suppose  $\Phi = 1E17$  n/cm<sup>2</sup>:  
do we replace the Silicon sensors 10 times at FCC?

**Question:**

**Can we design a Silicon tracker that can still work at**

$$\Phi = 1E17 \text{ n/cm}^2?$$



# Why is it possible? (maybe)

**The bottom line is:**

Silicon irradiated at fluences  $1E16 - 1E17$  n/cm<sup>2</sup> does not behave as expected,

**it behaves better**

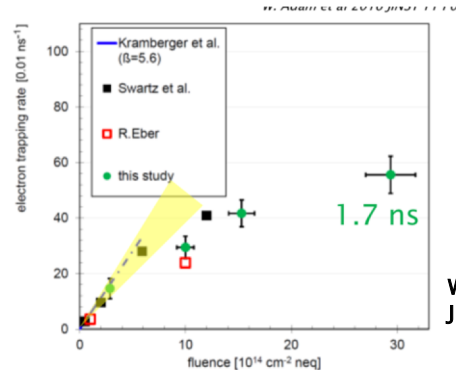
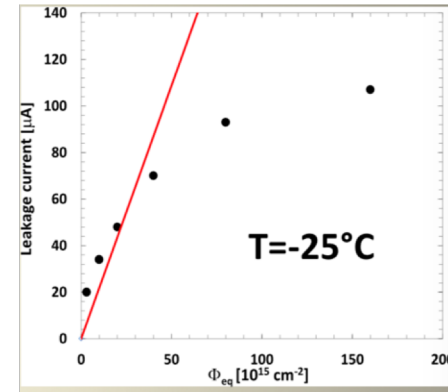
Extrapolations from Silicon sensors irradiated in the fluence range  $1E14 - 1E15$  n/cm<sup>2</sup> predict a hopeless situation

Examples:

1) Leakage current saturates

2) Trapping slows down

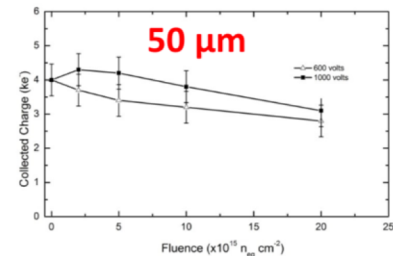
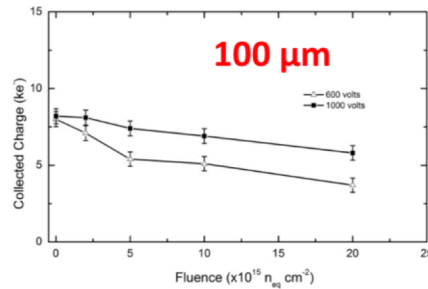
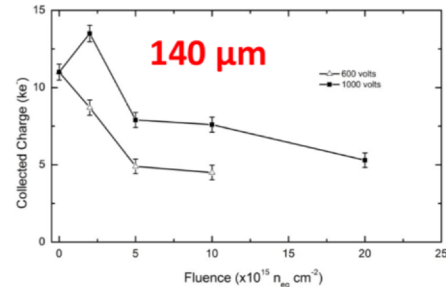
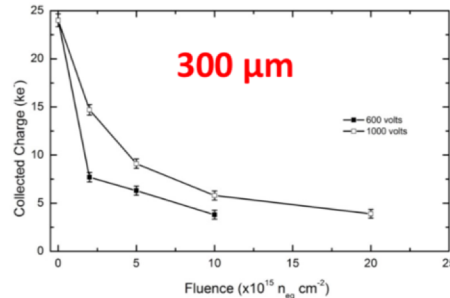
G. Kramerberger et al., *JINST 8 P08004 (2013)*.



W. Adam et al 2016  
JINST 11 P04023

# Example: CCE in Silicon up to $2E16$ n/cm<sup>2</sup>

## Degradation of the CC(V) with fluence at 600 and 1000V

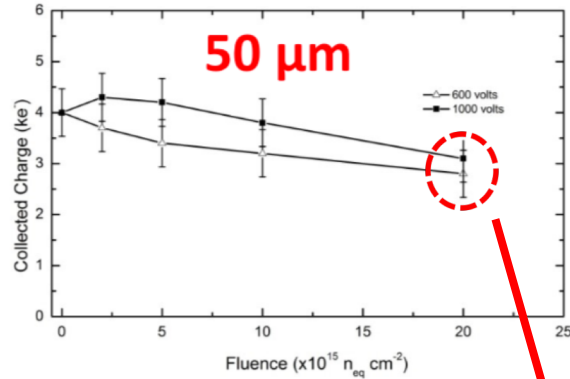


S. Wonsak, RD50, 02-04 Dez. 2015, CERN

**Note: regardless of the sensors thickness, the signal at  $2E16$  n/cm<sup>2</sup> is almost a constant, 3-5k electrons.**

# Why are the sensors still working?

The depletion is ~ 30 micron for every sensor thickness



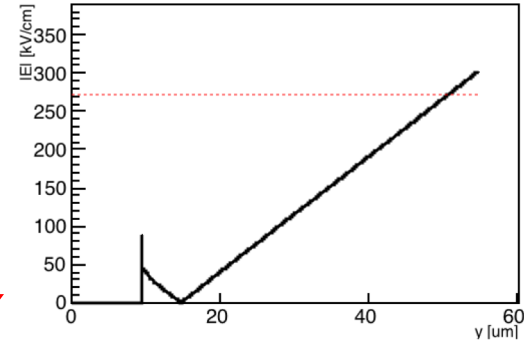
Consider the point at  $2\text{E}16 \text{ n/cm}^2$

According to low fluence models, the bulk should be doped  $N \sim 4\text{E}14 \text{ n/cm}^3$  and the Efield should be way above breakdown

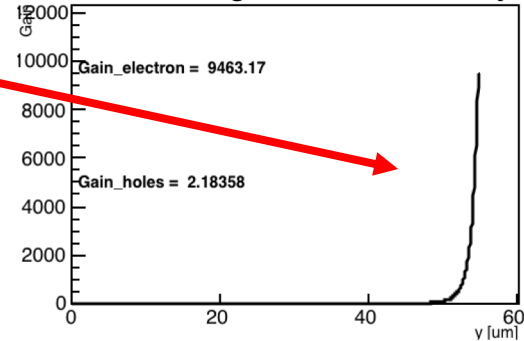
**It should not work, however it does...**

Less doped? Smaller mobility?

E Amplitude IEI [kV/cm] - Dashed: breakdown field



Incremental gain as a function of y



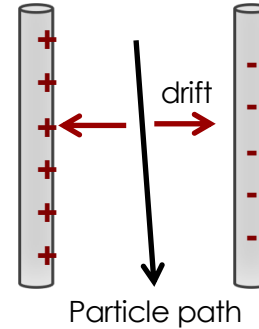
# The plan: use very thin sensors and gain..

At high fluences,  $1E16 - 1E17$  n/cm<sup>2</sup>, leakage current, bulk doping, and charge trapping are the enemies

- use thin sensors
- Signal too small

} Use gain

**3D sensors decouple drift path and total charge deposition** by collecting the charge carriers perpendicularly to the particle path.



**Can we decouple drift path and total charge deposition using gain?**

**Why this can be possible?**

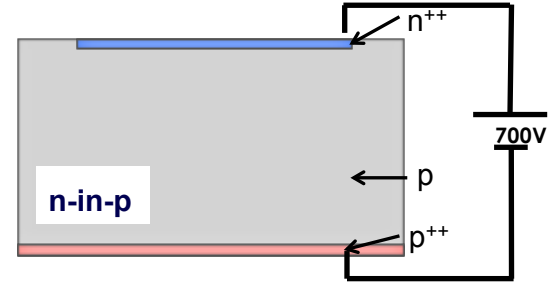
- The acceptors creation by irradiation slows down at high fluence, so the bulk is not as doped as we forecast
- Using  $V_{bias}$ , we can still start multiplication if the mobility stays high enough
- The charge to be delivered is rather small:  $\sim 1-2$  fC

# How to obtain gain in silicon: $E \sim 300\text{kV/cm}$

## 1) Use external bias:

$E_{\text{critical}} = \sim 10\text{-}15 \text{ V}/\mu\text{m}$

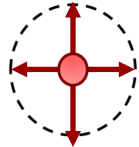
Possible only in thin sensors:  
50 microns need 500-750V



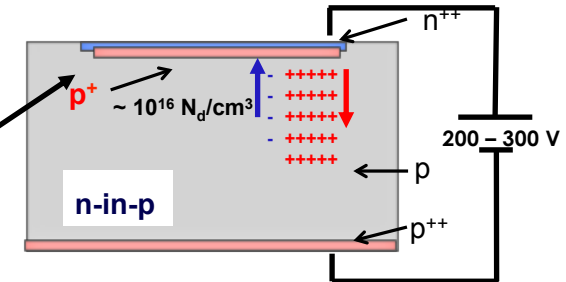
Traditional silicon detector

## 2) Use Gauss Theorem:

$$\sum q = 2\pi r * E$$



Gain in the gain layer

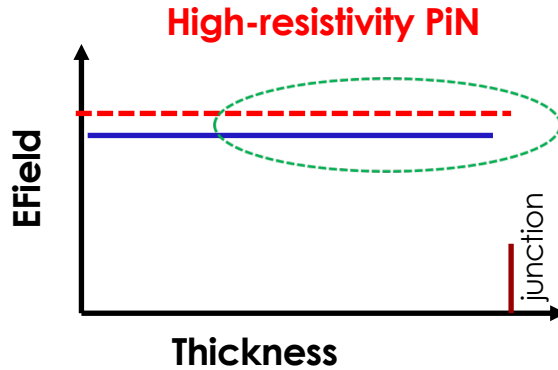
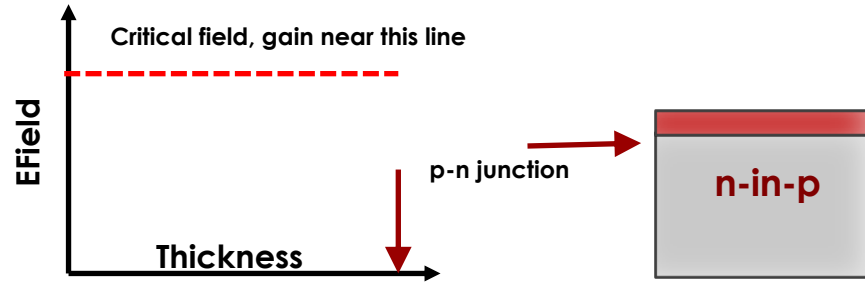


Low gain avalanche detectors

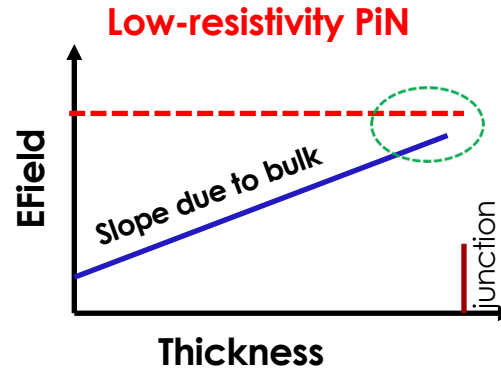
$E = 300 \text{ kV/cm} \rightarrow q \sim 10^{16} /\text{cm}^3$

The doping of the bulk will generate the field

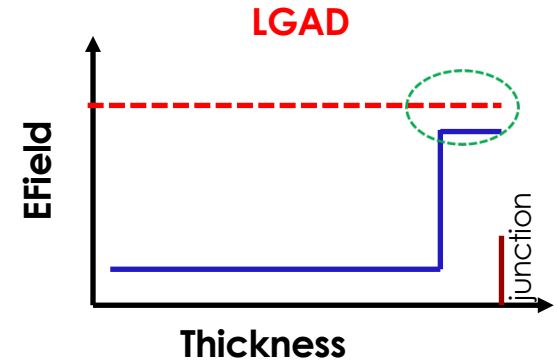
# Gain and $E_{field}$ in Si detector: combination of Bias and doping



Field due to  $V_{bias}$   
No contribution from bulk

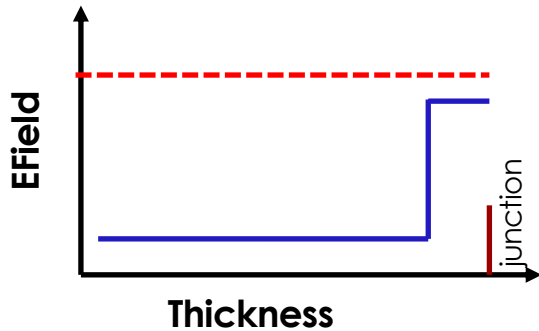


Field due to  $V_{bias}$  **and**  
contribution from bulk

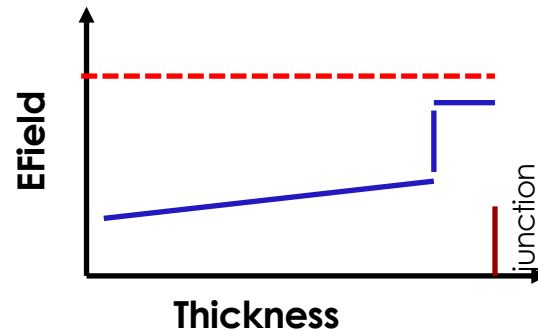


Field due to  $V_{bias}$  **and**  
gain layer doping

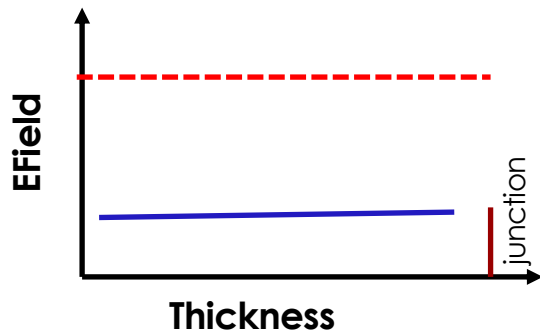
# Effect of radiation: increase bulk doping and gain layer removal



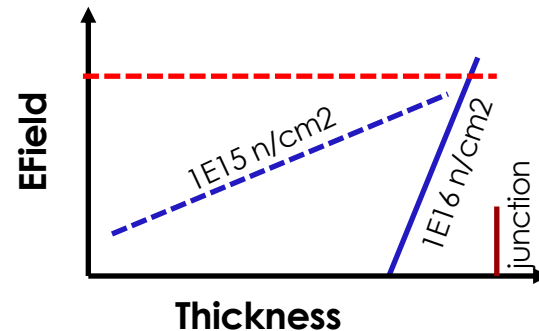
irradiation



Let's start with an LGAD, n-in-p



irradiation



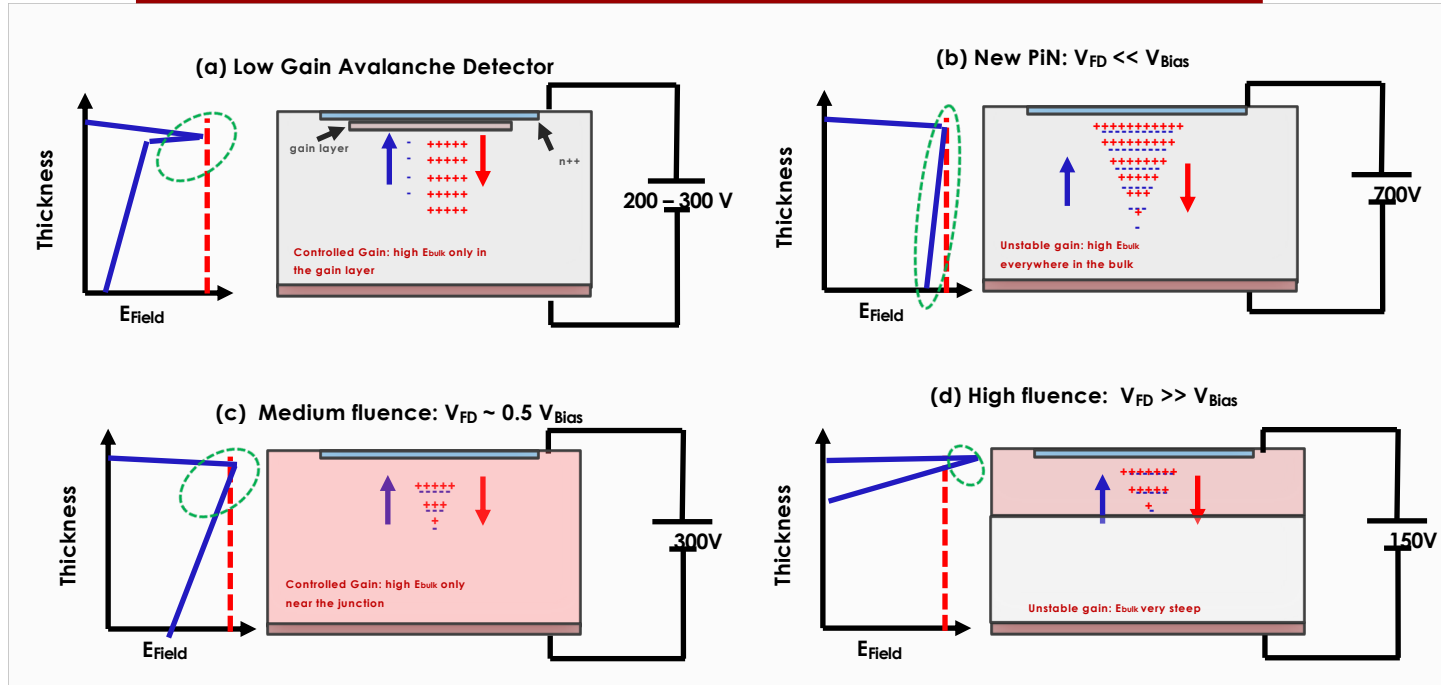
Fluence  $\sim 1E15 \text{ n/cm}^2$  removes the gain layer and add p-doping to the bulk

High resistivity silicon has very flat field

Fluence  $\sim 1E16 \text{ n/cm}^2$  the bulk is so doped it cannot be depleted

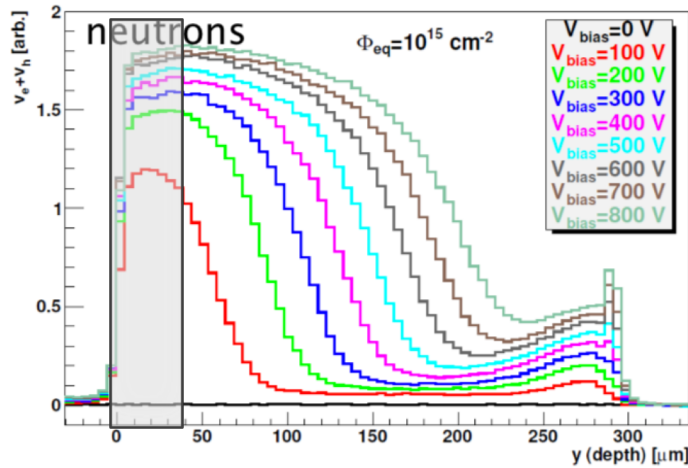


# Gain and $E_{\text{field}}$ in various sensors

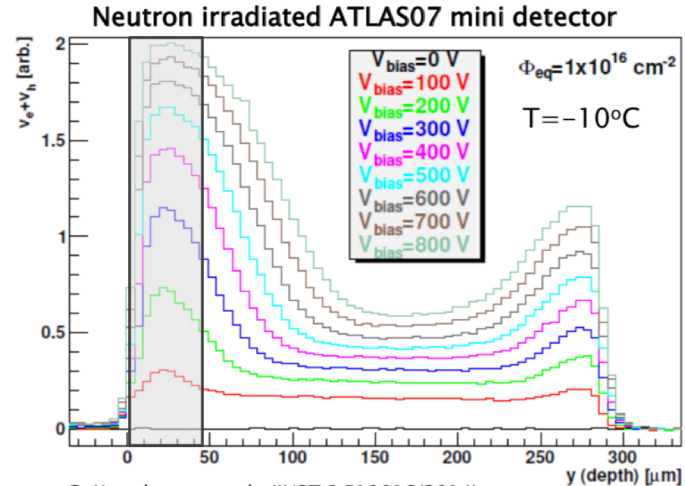


**Controlled gain: it happens when** the  $E_{\text{field}}$  is controllable by  $V_{\text{bias}}$  and the contribution of the doping to the field accounts for a part ( $\sim 50\%$ ) of the total  $E_{\text{field}}$

# E Fields vs irradiation



G. Kramerger et al., JINST 9 P10016(2014).



G. Kramerger et al., JINST 9 P10016(2014).

The field changes a lot, due to the appearance of the “double junction”, caused by high leakage current.

Look at the first 20-40  $\mu\text{m}$ : very uniform field

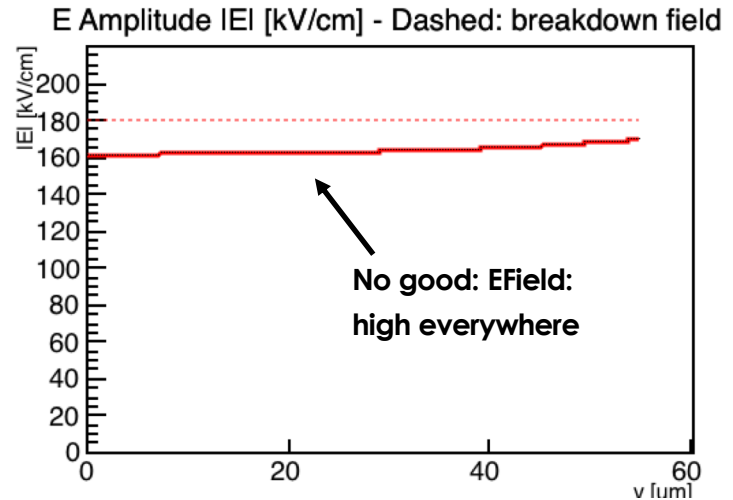
# What type of Si detector can deliver 1 fC from un-irradiated to a fluence = $1E17n/cm^2$

We need to have a plan to deliver **at least 1 fC** throughout the sensor lifetime. In thin sensors you need to have always gain

## Can we use a thin PiN diode?

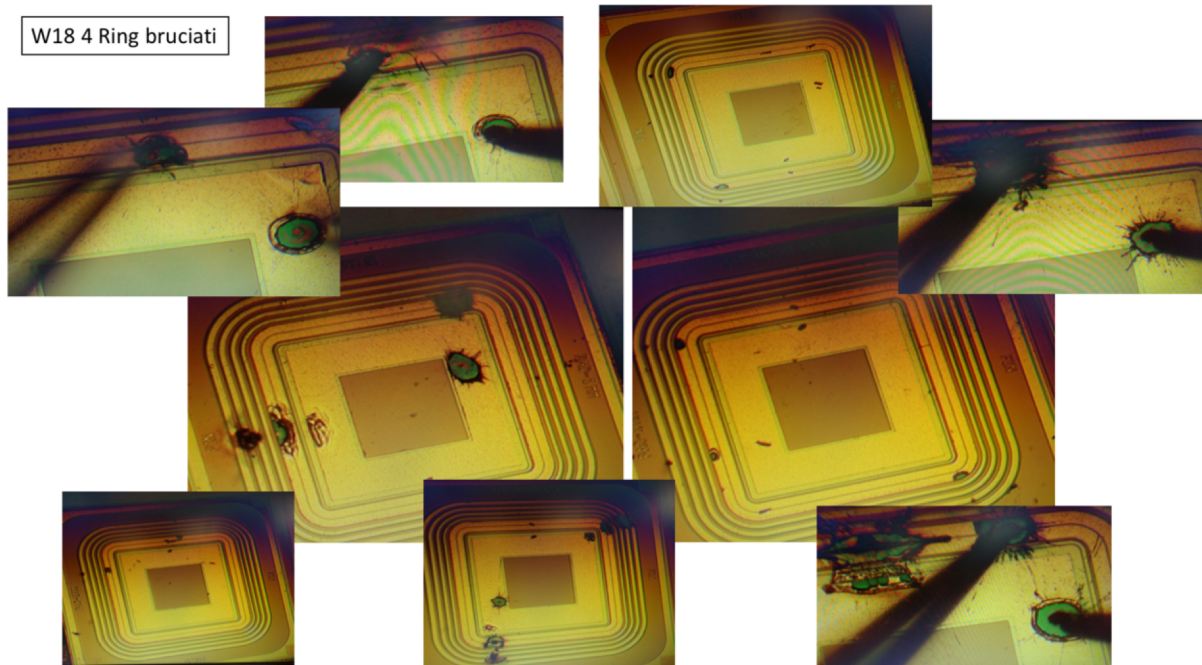
In high resistivity silicon, the field is almost constant in the sensor,

- It reaches the critical value at the same voltage everywhere in the detector
- It burns the sensors



# Is gain in high-resistivity PIN reliable?

W18 4 Ring bruciati



**Not really.... We cannot start with a thin PiN diode**

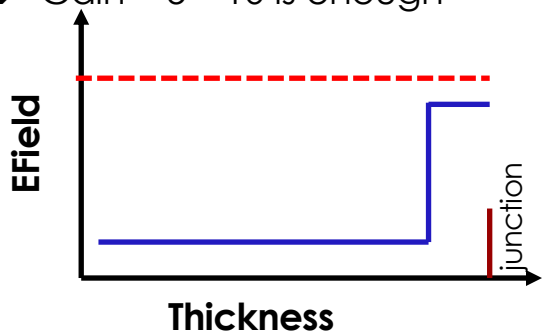
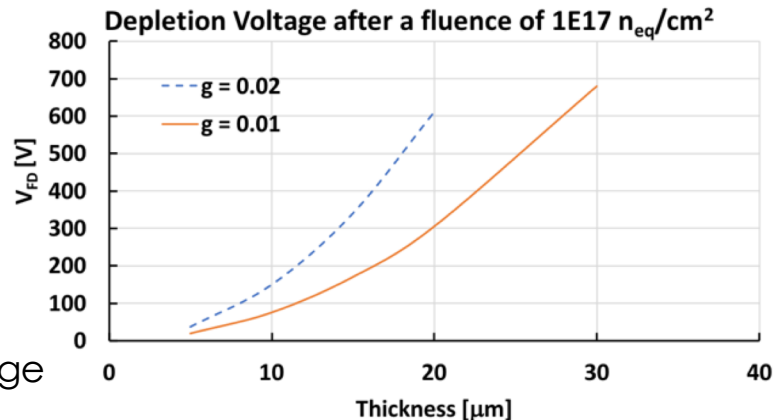
# The plan - I

- Select a thickness that can still be depleted after a fluence  $\sim 1E17$  n/cm<sup>2</sup>
- Bias should be in control of the multiplication mechanism

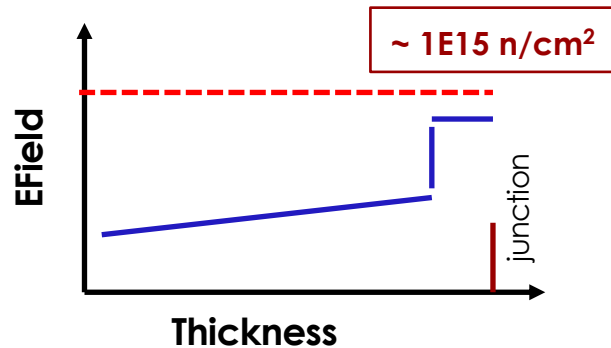
Assuming standard rate of acceptor creation a thickness of  $\sim 20$  micron should be OK

Such thin detector will not provide enough charge

- ➔ use an LGAD of  $\sim 20$ - $30$  micron ( $0.2 - 0.3$  fC)
- ➔ Gain  $\sim 5 - 10$  is enough



$\sim 1E15$  n/cm<sup>2</sup>  
irradiation



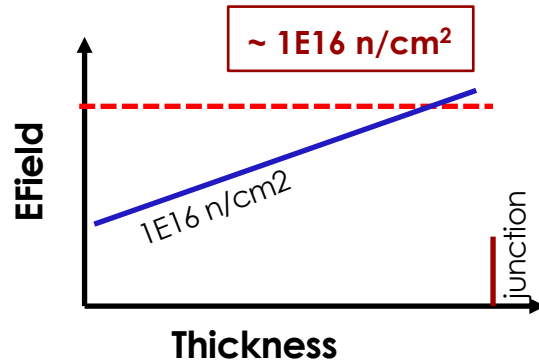
Let's start with an LGAD, n-in-p

Less gain layer and more p-doping to the bulk

# The plan - II

## 2) In the $\sim 0.5- 1E16 \text{ n/cm}^2$

- The gain layer doping is removed
- The gain from  $V_{\text{bias}}$  and the bulk doping starts to be important

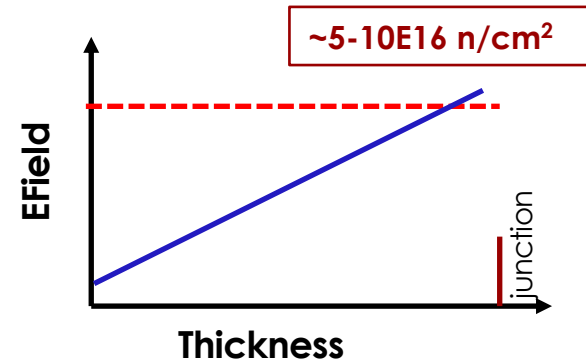


the bulk contribution start to be important

## 3) Above $5-10 E15 \text{ n/cm}^2$ : this is the fun part...

### Condition to have gain:

1. High  $E_{\text{field}}$
2. the width of a space charge region  $\gg$  the mean free path between two ionizing impacts



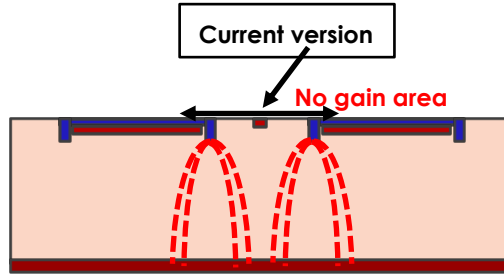
Limiting fluence: Bias barely manages to deplete the sensors

Irradiation decreases the mean free path, so even if the field is high, the sensors are not in breakdown, the gain is quenched, but maybe still reachable in thin sensors

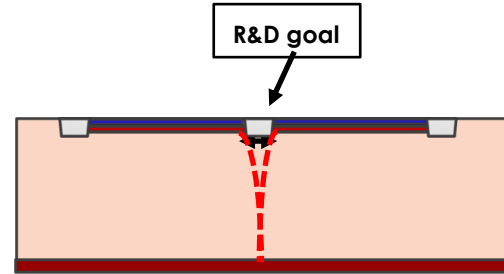
# Gain termination for 100% fill factor: trenches

**Trenches** (the same technique used in SiPM):

- No pstop,
- No JTE → no extra electrode bending the field lines



JTE + p-stop design

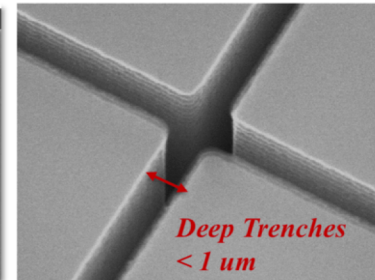
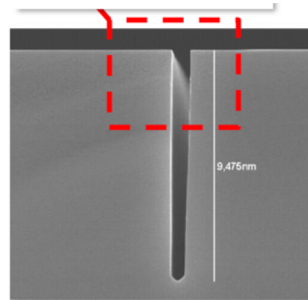


Trench design

## Trench isolation technology

- Typical trench width < 1  $\mu\text{m}$
- Max Aspect ratio: 1:20
- Trench filling with:  $\text{SiO}_2$ ,  $\text{Si}_3\text{N}_4$ , PolySi

CMM  
CENTRE FOR MATERIALS AND MICROSYSTEMS



**Goal: design a simple sensor that can deliver good signals for fluences  $1E16 - 1E17 \text{ n/cm}^2$**

In the sensor lifetime, there will be the interplay of 3 types of gain:

- Due to Gain Layer
- Due to  $V_{\text{bias}}$
- Due to the bulk doping

## Below $2E15 \text{ n/cm}^2$

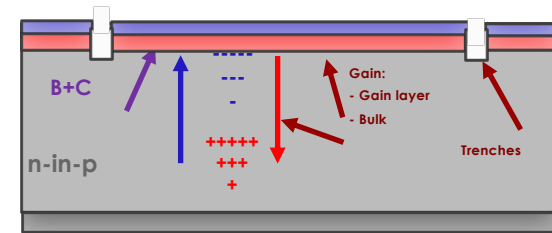
- Start with thin LGAD sensors
- It looks possible to have a gain of  $\sim 5$  without breakdown
- $V_{\text{bias}}$  and gain layer doping controls gain

## Range $5 - 10E15 \text{ n/cm}^2$

- The initial gain layer is disactivated,
- gain comes from  $V_{\text{bias}}$  and bulk doping

## above $1E16 \text{ n/cm}^2$

- is the gain still there?
- Is the mobility decreasing to a point where no gain is possible?
- Damaged bulk acts as a quenching resistor?
- No holes multiplications?



**25 microns LGAD trench sensor**

**Good signal above  $1E16 \text{ n}_{\text{eq}}/\text{cm}^2$  ?**



# Acknowledgement

---

- Part of this work has been financed by the European Union's Horizon 2020 Research and Innovation funding program, under
  - Grant Agreement no. 654168 (AIDA-2020)
  - Grant Agreement no. 669529 (ERC UFSD669529)
- Italian Ministero degli Affari Esteri
- INFN Gruppo V

